
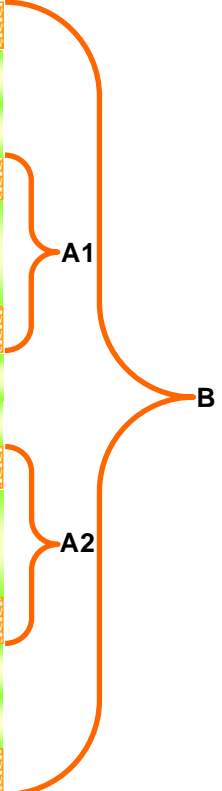


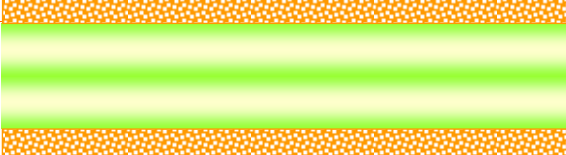
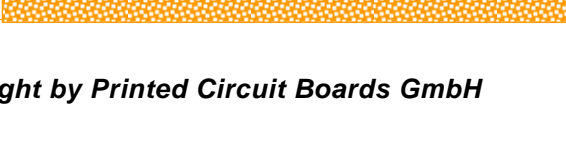



Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
06	155	FR4	35	L41.35	P10_06	S1
columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.						
06_155_FR4_35_L41.35_p10_06_s1						

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper	 (100 μ PrePreg-Type: 2125)	A1
	100 μ	Prepreg		
	100 μ	Prepreg		A1
Layer-2	35 μ	Copper		
	410 μ	L-FR4	 (60 μ PrePreg-Type: 1080)	B
Layer-3	35 μ	Copper		
	60 μ	Prepreg		A2
Layer-4	35 μ	Copper		
	410 μ	L-FR4		A2
Layer-5	35 μ	Copper		
	100 μ	Prepreg		A2
	100 μ	Prepreg		
Layer-99	35 μ	Copper		A2

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